IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re Application of

Joseph Young J. PAIK

Serial No. 10/665,165 : Group Art Unit:

Filed: September 18, 2003 : Examiner:

For: FEEDBACK CONTROL OF A CHEMICAL MECHANICAL POLISHING PROCESS FOR MULTI-LAYERED FILMS

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of any cited U.S. Patents and U.S. Patent Publications are not being submitted in accordance with 37 CFR 1.98(a)(2)(i).

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R.§ 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of

Serial No. 10/665,165

publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

The references listed on Sheet 1 of the attached PTO-1449 Forms were cited in a patentability investigation and/or a corresponding foreign or PCT application relating to the above-referenced application. The remaining references are from potentially related patent applications, and possibly other sources.

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

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SHEET <u>1</u> OF <u>26</u>

JUN 1 6 2014 BY TRADEMINATION

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)

ATTY. DOCKET NO.
007734 FPS/MMCS/APC

APPLICANT
Joseph Young J. PAIK

FILING DATE

GROUP

U.S. PATENT DOCUMENTS

September 18, 2003

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SHEET 2 OF 26

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	(110	1110)		APPLICANT Joseph Your	ng J. PAIK	.1	
				FILING DATE September 1	8, 2003	GROUP	
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SHEET <u>3</u> OF <u>26</u>

GROUP

INFORMATION DISCLOSURE CITATION IN AN **APPLICATION** (PTO-1449)

ATTY. DOCKET NO. SERIAL NO. 007734 FPS/MMCS/APC 10/665,165 APPLICANT Joseph Young J. PAIK

FILING DATE

September 18, 2003

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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SHEET 4 OF 26

ATTY. DOCKET NO. SERIAL NO. INFORMATION DISCLOSURE 007734 FPS/MMCS/APC 10/665,165 CITATION IN AN **APPLICATION** (PTO-1449) **APPLICANT** Joseph Young J. PAIK FILING DATE **GROUP** September 18, 2003 **U.S. PATENT DOCUMENTS EXAMINER'S FILING INITIALS** PATENT NO. DATE **NAME** DATE **CLASS SUBCLASS** 5,546,312 08/13/96 Mozumder et al. 02/24/94 5,553,195 09/03/96 Meijer 09/29/94 5,586,039 12/17/96 Hirsch et al. 02/27/95 5,599,423 02/04/97 Parker et al. 06/30/95 Cresswell et al. 5,602,492 02/11/97 04/28/94 5,603,707 02/18/97 Trombetta et al. 11/28/95 5,617,023 04/01/97 Skalski 02/02/95 5,627,083 05/06/97 Tounai 05/12/95 5,629,216 05/13/97 Wijaranakula et al. 02/27/96 5,642,296 06/24/97 Saxena 07/29/93 5,646,870 Krivokapic et al. 07/08/97 02/13/95 5,649,169 07/15/97 Berezin et al. 06/20/95 5,654,903 Reitman et al. 08/05/97 11/07/95 5,655,951 Meikle et al. 08/12/97 09/29/95 5,657,254 08/12/97 Sierk et al. 04/15/96 5,661,669 08/26/97 Mozumder et al. 06/07/95 5,663,797 09/02/97 Sandhu 05/16/96 5,664,987 09/09/97 Renteln 09/04/96 5,666,297 09/09/97 Britt et al. 05/13/94 5,667,424 09/16/97 Pan 09/25/96 5,674,787 10/07/97 Zhao et al. 01/16/96 5,694,325 12/02/97 Fukuda et al. 11/22/95 5,698,989 12/16/97 09/13/96 Nulman 5,719,495 02/17/98 Moslehi 06/05/96 5,719,796 02/17/98 Chen 12/04/95 5,735,055 04/07/98 Hochbein et al. 04/23/96 5,740,429 04/14/98 Wang et al. 07/07/95 **EXAMINER DATE CONSIDERED**

SHEET <u>5</u> OF <u>26</u>

SERIAL NO. ATTY. DOCKET NO. INFORMATION DISCLOSURE 007734 FPS/MMCS/APC 10/665,165 CITATION IN AN **APPLICATION** (PTO-1449) APPLICANT Joseph Young J. PAIK **FILING DATE GROUP** September 18, 2003 **U.S. PATENT DOCUMENTS EXAMINER'S FILING** INITIALS PATENT NO. **DATE NAME** DATE **CLASS SUBCLASS** 5,751,582 05/12/98 Saxena et al. 09/24/96 5,754,297 Nulman 04/14/97 05/19/98 5,761,064 06/02/98 La et al. 10/06/95 5,761,065 06/02/98 Kittler et al. 03/30/95 5,764,543 06/09/98 Kennedy 06/16/95 5,777,901 07/07/98 Berezin et al. 09/29/95 5,787,021 07/28/98 12/18/95 Samaha 5,787,269 Hyodo 07/28/98 09/19/95 5,808,303 09/15/98 Schlagheck et al. 01/29/97 5,812,407 09/22/98 Sato et al. 08/12/97 5,823,854 10/20/98 Chen 05/28/96 5,825,913 10/20/98 Rostami et al. 07/18/95 5,828,778 10/27/98 Hagi et al. 07/12/96 5,832,224 Fehskens et al. 11/03/98 06/14/96 5,838,595 Sullivan et al. 11/17/98 11/25/96 5,844,554 12/01/98 Geller et al. 09/17/96 5,857,258 01/12/99 05/12/94 Penzes et al. 5,859,964 01/12/99 Wang et al. 10/25/96 5,859,975 01/12/99 Brewer et al. 08/09/96 5,862,054 01/19/99 Li 02/20/97 5,863,807 01/26/99 Jang et al. 03/15/96 5,867,389 02/02/99 Hamada et al. 11/26/96 5,870,306 02/09/99 Harada 06/13/97 5,883,437 03/16/99 Maruyama et al. 12/28/95 5,889,991 03/30/99 Consolatti et al. 12/06/96 5,901,313 05/04/99 Wolfe et al. 09/02/97 5,903,455 05/11/99 Sharpe, Jr. et al. 12/12/96 5,910,011 06/08/99 Cruse 05/12/97 5,910,846 06/08/99 Sandhu 08/19/97 **EXAMINER DATE CONSIDERED**

SHEET <u>6</u> OF <u>26</u>

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)

ATTY. DOCKET NO. 007734 FPS/MMCS/APC SERIAL NO. 10/665,165

APPLICANT

Joseph Young J. PAIK

FILING DATE
September 18, 2003

GROUP

U.S. PATENT DOCUMENTS

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SHEET <u>7</u> OF <u>26</u>

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)		ATTY. DOCKET 007734 FPS/MI		SERIAL NO 10/665,10			
	(1 10-)	(44 7)		APPLICANT Joseph Young	g J. PAIK		
				FILING DATE September 18	3, 2003	GROUP	
		1	J.S. PATENT	DOCUMENTS			
EXAMINER'S INITIALS	PATENT NO.	DATE		NAME	CLASS	CHIDGLAGG	FILING
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SHEET <u>8</u> OF <u>26</u> SERIAL NO. ATTY. DOCKET NO. INFORMATION DISCLOSURE 007734 FPS/MMCS/APC 10/665,165 CITATION IN AN APPLICATION (PTO-1449) **APPLICANT** Joseph Young J. PAIK FILING DATE **GROUP** September 18, 2003 U.S. PATENT DOCUMENTS **EXAMINER'S FILING** INITIALS PATENT NO. DATE **NAME CLASS** DATE **SUBCLASS** 6,226,792 B1 Goiffon et al. 05/01/01 10/14/98 6,236,903 B1 Kim et al. 05/22/01 09/25/98 05/24/01 2001/0001755 A1 Sandhu et al. 12/29/00 6,240,330 B1 05/29/01 Kurtzberg et al. 05/28/97 6,240,331 B1 05/29/01 Yun 08/18/98 06/07/01 2001/0003084 A1 **Finarov** 12/04/00 6,245,581 B1 06/12/01 Bonser et al. 04/19/00 6,246,972 B1 06/12/01 Klimasauskas 05/27/99 6,248,602 B1 06/19/01 Bode et al. 11/01/99 6,249,712 B1 06/19/01 Boiquaye 09/25/96 6,252,412 B1 06/26/01 Talbot et al. 01/08/99 6,253,366 B1 06/26/01 Mutschler, III 03/31/99 6,263,255 B1 07/17/01 Tan et al. 05/18/98 6,271,670 B1 08/07/01 Caffey 02/08/99 6,276,989 B1 Campbell et al. 08/21/01 08/11/99 6,278,899 B1 Piche et al. 08/21/01 10/06/98 6,280,289 B1 08/28/01 Wiswesser et al. 11/02/98 6,284,622 B1 09/04/01 Campbell et al. 10/25/99 6,287,879 B1 09/11/01 Gonzales et al. 08/11/99 6,292,708 B1 09/18/01 Allen et al. 06/11/98 6,298,274 B1 10/02/01 Inoue 09/01/99 6,298,470 B1 10/02/01 Breiner et al. 04/15/99 6,303,395 B1 10/16/01 Nulman 06/01/99 6,304,999 B1 Toprac et al. 10/16/01 10/23/00 2001/0030366 A1 10/16/01 Nakano et al. 03/07/01

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

DATE CONSIDERED

Lu et al.

Hu et al.

10/23/01

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EXAMINER

SHEET 9 OF 26 ATTY. DOCKET NO. SERIAL NO. INFORMATION DISCLOSURE 007734 FPS/MMCS/APC 10/665,165 CITATION IN AN **APPLICATION** (PTO-1449) **APPLICANT** Joseph Young J. PAIK FILING DATE **GROUP** September 18, 2003 **U.S. PATENT DOCUMENTS EXAMINER'S FILING INITIALS** PATENT NO. DATE **NAME CLASS** DATE **SUBCLASS** 2001/0040997 A1 11/15/01 Tsap et al. 05/15/01 6,320,655 B1 11/20/01 Matsushita et al. 03/15/00 2001/0042690 A1 11/22/01 Talieh 12/14/00 Nakano et al. 2001/0044667 A1 11/22/01 05/16/01 6,324,481 B1 Atchison et al. 11/27/01 06/15/99 6,336,841 B1 01/08/02 Chang 03/29/01 6,340,602 B1 01/22/02 Johnson et al. 02/12/01 6,345,288 B1 02/05/02 Reed et al. 05/15/00 02/05/02 6,345,315 B1 Mishra 08/12/98 Toprac et al. 6,346,426 B1 02/12/02 11/17/00 03/14/02 Wilson et al. 2002/0032499 05/04/01 6,360,133 B1 03/19/02 Campbell et al. 06/17/99 6,360,184 B1 03/19/02 Jacquez 03/26/97 6,363,294 B1 03/26/02 Coronel et al. 12/29/98 6,366,934 B1 04/02/02 Cheng et al. 06/02/99 6,368,879 B1 04/09/02 Toprac 09/22/99 6,368,883 B1 04/09/02 Bode et al. 08/10/99 6,368,884 B1 04/09/02 Goodwin et al. 04/13/00 6,388,253 B1 05/14/02 11/02/00 Su 6,389,491 B1 05/14/02 Jacobson et al. 03/23/99 6,395,152 B1 05/28/02 Wang 07/02/99 6,397,114 B1 05/28/02 Eryurek et al. 05/03/99 06/04/02 6,400,162 B1 Mallory et al. 07/21/00 6,405,096 B1 06/11/02

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

Toprac et al.

Toprac et al.

DATE CONSIDERED

06/11/02

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SHEET <u>10</u> OF <u>26</u>

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)		ATTY. DOCKET 007734 FPS/M		SERIAL NO 10/665,16			
	(110-14	+'+ '7)		APPLICANT Joseph Youn	g J. PAIK	1	
				FILING DATE September 18	8, 2003	GROUP	
		Ţ	J.S. PATENT D	OCUMENTS		<u> </u>	
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